REMARKS

Acknowledgment of the foreign priority claim and receipt of the priority document is respectfully requested. In this connection, the attention of the Examiner is respectfully invited to page 2 of the Request for Continuing Application under 37 C.F.R. § 153(b). At present, the record acknowledges domestic priority but not foreign priority under 35 U.S.C. § 119.

Claim 6 has been amended to provide antecedent basis for the reference to the porous structure in claim 7. As a result, it is respectfully submitted that the rejection under 35 U.S.C. § 112 should be withdrawn.

The rejection of claims 6, 7, 12 and 16-18 under 35 U.S.C. § 102 as being anticipated by Prakash, et al. (U.S. 4,517,155) is respectfully traversed.

The Prakash reference relates to a copper base metal termination for multilayer ceramic capacitors. These are multilayer monolithic structures containing a plurality of internal electrodes which are connected to an end metallization (terminal electrode) on the surface of the capacitor. The end metallization is obtained by providing a copper containing termination paste, applying the paste to a portion of the multilayer capacitor body containing a multiplicity of internal electrodes and then heating the copper paste. As clearly appears in the drawings of this reference, only a single layer external electrode is achieved. The terminal electrode in this reference is not multilayered – the terminology "a multi-electrode" refers to the fact that the capacitors have a multiplicity of electrodes rather than any particular electrode being multilayer.

The description of the Prakash patent in the Office Action is not understood in that column/line citations do not appear to support the proportions for which they were cited. For example, the Office Action asserts that Prakash shows forming an "inherent"

first conductive paste film via film composed of multiple first, second and third contiguous layers. Nothing in the reference, whether in the text or in the drawings, shows anything more than a single external electrode layer. At best, it potentially could be argued that the exposed portion of the internal electrodes constitute a first layer and the fired end metallization constitutes a second layer but, even if this was a valid interpretation, it would not be relevant to the instant claims. Likewise, while the Action asserts there is disclosure of ".5 to 6 micro meters", the only metal particle size noted is a broad statement that copper powders having particle sizes ranging from about 10 microns exist (without suggesting any particular particle size be selected). The foregoing are only examples of portions of the Office Action where the assertions do not match the cited column and lines.

Prakash does not teach or suggest producing a ceramic electronic component chip having internal wiring connected to a terminal electrode on the outer surface by providing the electronic component having inner wiring, forming a first conductive film containing conductive particles on a portion of the outer surface, forming a second conductive paste layer containing conductive particles and an additive which burns out upon baking, forming a third conductive paste layer and baking the resulting composite.

Claims 6-19 were rejected under 35 U.S.C. § 103 over TDK (JP '881) in combination with Prakash '155. This rejection is respectfully traversed.

The TDK patent relates to a process which involves coating a conductive paste comprising a base metal powder, glass frit and organic vehicle on a substrate and then heating the paste to burn out the vehicle. Nothing in the English title, abstract or figures of this reference teaches or suggests or has any reference to a terminal electrode which has multiple layers.

Because of these basic deficiencies in the references, no further discussion appears to be necessary.

It is believed that this application is now in condition to be allowed and the early issuance of a Notice of Allowance is respectfully solicited.

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Respectfully submitted,

By 

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